


**TRANSMITTAL**

Electronic Version v1.1

Stylesheet Version v1.1.0

<b>Title of Invention</b>	<b>ANOLYTE FOR COPPER PLATING</b>		
Application Number : 10/616044 			
Date : 2003-07-08			
First Named Applicant: Mr. Yang Michael X.			
Confirmation Number: 9799			
Attorney Docket Number: APPM/7669P2			
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Submitted By:		Elec. Sign.	
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Documents being submitted:	Files
us-ids	APPM7669P2BTP-usidst.xml us-ids.dtd us-ids.xsl
us-fee-sheet	APPM7669P2BTP-usfees.xml us-fee-sheet.xsl us-fee-sheet.dtd
Comments	